

GSDBAV99J4F

Switching Diode

Product Description

Switching Diode 75V and 150mA

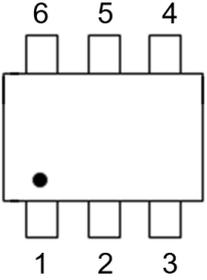
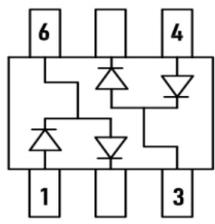
Features

- Rugged and Reliable

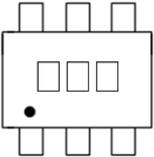
Mechanical Data

- SOT-363 Package
- RoHS Compliant and Halogen Free

Package and Pin Assignment

SOT-363		Equivalent Circuit	
			
Pin	Description	Pin	Description
1	Anode 1	6	Common 1
2	Cathode 1	5	Cathode 2
3	Common 2	4	Anode 2

Ordering and Marking Information

GS P/N	Package	Marking	Quantity / Reel
GSDBAV99J4F	SOT-363	KJG	3,000PCS
GSDBAV99J4F			
- Product Code: GSDBAV99	- Package Code: J4 for SOT-363	- Green Level: F for RoHS Compliant and Halogen Free	
Marking Information			
	- Product Code: □□□ is KJG - Dot denotes Pin 1		

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit
V _R	Reverse Voltage	75	V
I _o	Forward Current	150	mA
I _{FSM}	Non-Repetitive Peak Forward Current (8.3ms single half sin-wave)	2	A
P _D	Power Dissipation	200	mW
T _J	Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

Electrical Characteristics (T_A=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{BR}	Breakdown Voltage	I _R =100μA	75			V
V _F	Forward Voltage	I _F =150mA			1.25	V
I _R	Reverse Current	V _R =75V			2.5	μA
C _J	Junction Capacitance	V _R =0V, f=1MHz			2	pF
t _{rr}	Reverse Recovery Time	I _F =I _R =10mA, I _{rr} =0.1×I _R , R _L =100Ω			4	ns

Typical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

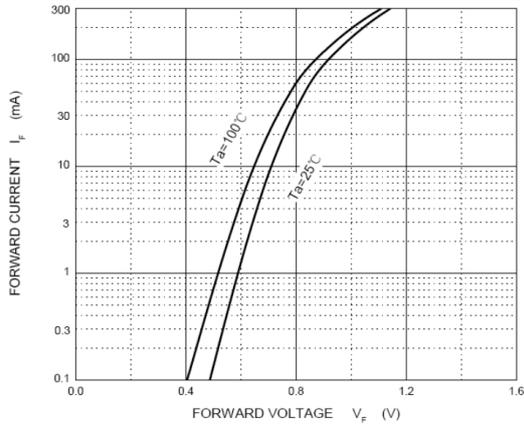


FIG.1 Forward Characteristics

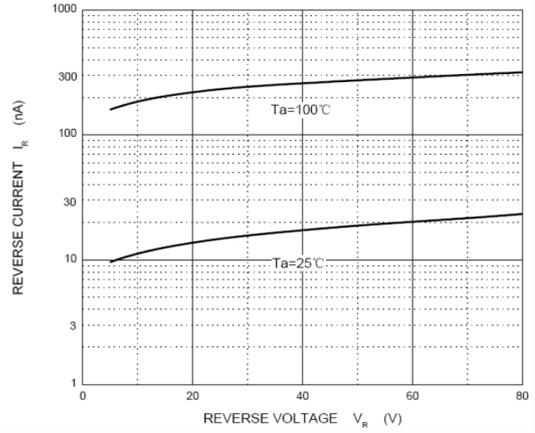


FIG.2 Reverse Characteristics

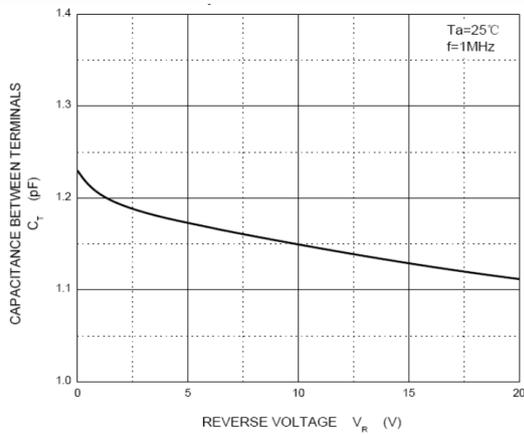


FIG.3 Capacitance Characteristics

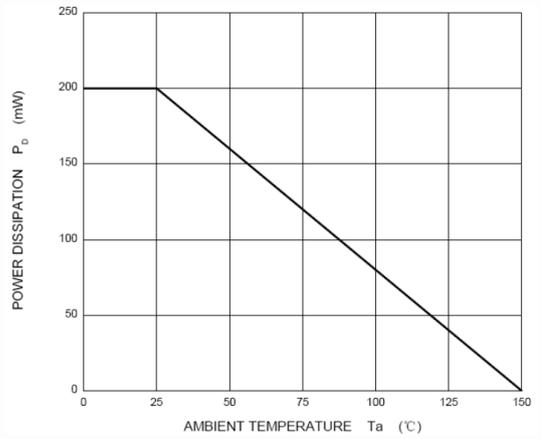
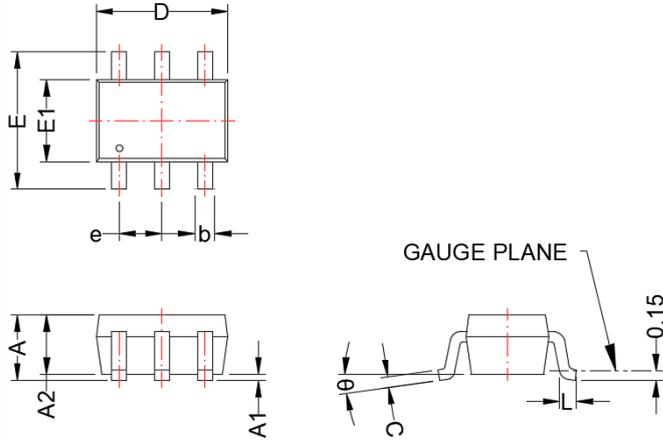


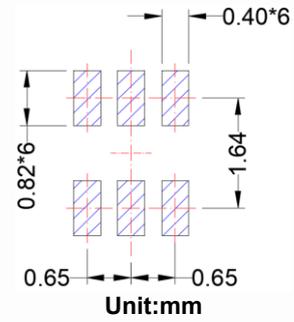
FIG.4 Power Derating Curve

SOT-363

Package Dimension



Recommended Land Pattern



Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.80	1.10	0.031	0.043
A1	0.00	0.10	0.000	0.004
A2	0.70	1.00	0.028	0.039
b	0.15	0.30	0.006	0.012
c	0.08	0.25	0.003	0.010
D	1.80	2.20	0.071	0.087
E	1.80	2.40	0.071	0.094
E1	1.15	1.35	0.045	0.053
e	0.65 BSC		0.026 BSC	
L	0.26	0.46	0.010	0.018
θ	0°	8°	0°	8°

NOTE:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

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